ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1 Stylesheet Version v1.1.1

Title of Invention

HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER

Submision Type: Information Disclosure

Statement

Application Number:

10/680783

EFS ID: Server Response: 74421

Confirmation	Message		
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ISVNI	Submission was successfully submitted - Even if Informational or Warning Messages		
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ICON1	5859		
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First Named Applicant:

William Jones

Attorney Docket Number:

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File Listing:	Doc. Name	File Name	Size (Bytes)	Date Produced
	us-ids	SSI04001-usidst.xml	2/60	(yyyymmdd) 2004-12-16
	us-ids	us-ids.dtd		2004-12-16
	us-ids	us-ids.xsl		2004-12-16
	package-data	SSI04001-pkda.xml		2004-12-16
	package-data	package-data.dtd		2004-12-16
	package-data	us-package-data.xsl	19263	2004-12-16
		Total file	s size 70252	
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